



L	Hits	Search Text	DB	Time stamp
Number	509414	semiconductor and substrate	USPAT;	2003/08/15
-	309414	Semiconductor and Substrate	US-PGPUB;	13:15
			EPO; JPO;	13.13
			DERWENT;	
			IBM TDB	
	1293	passive same interconnect\$4 same	USPAT;	2003/08/15
	1293	substrate	US-PGPUB;	13:15
		substrate	EPO; JPO;	13.13
			1	
			DERWENT;	
			IBM_TDB	1 2000 100 115
-	135	trench same encircle\$1	USPAT;	2003/08/15
			US-PGPUB;	13:16
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	(semiconductor and substrate) and	USPĀT;	2003/08/15
		(passive same interconnect\$4 same	US-PGPUB;	13:16
		substrate) and (trench same encircle\$1)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1	(passive same interconnect\$4 same	USPAT;	2003/08/15
	-	substrate) and (trench same encircle\$1)	US-PGPUB;	13:16
		Substrace, and (trench same encircled)	EPO; JPO;	13.10
			DERWENT;	
	0.5	(IBM_TDB	2003/08/15
	85	\	USPAT;	
		(trench same encircle\$1)	US-PGPUB;	13:17
			EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
-	78	((semiconductor and substrate) and	USPAT;	2003/08/15
		(trench same encircle\$1)) and layer\$1	US-PGPUB;	13:17
			EPO; JPO;	
			DERWENT;	
	1 -2		IBM_TDB	
-	30	(((semiconductor and substrate) and	USPAT;	2003/08/15
		(trench same encircle\$1)) and layer\$1)	US-PGPUB;	13:17
		and interconnect\$4	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	27	((((semiconductor and substrate) and	USPAT;	2003/08/15
		(trench same encircle\$1)) and layer\$1)	US-PGPUB;	13:18
		and interconnect\$4) and @ad<=20010418	EPO; JPO;	
			DERWENT;	
			IBM TDB	